



Package Material Composition and Mass Calculation

Customer : NVL
 Package : VFAQFN 73L 7x7x0.8PKG
 Device Type : nRF52833-QIAA#3X
 Die Size(mm) : 3.192x3.192
 Total Pkg. Wt (mg): 118.80186

Provided By : Anna Chang
 Date : 8/20/2019
 Rev. :

name	vendor	material composition	CAS No.	%	mg.(ave)	mg.	%	PPM	SGS Report
Mold Compound	EME-G700LA TypeL-A	SUMITOMO	Epoxy Resin	Trade secret	5-10%	5.95350	66.15	55.681%	556,809
			Phenol Resin	Trade secret	1-5%	1.98450		5.011%	50,113
			Silica(Amorphous) A	60676-86-0	70-80%	52.06005		1.670%	16,704
			Silica(Amorphous) B	7631-86-9	5-10%	5.95350		43.821%	438,209
			Carbon black	1333-86-4	0.1 - 1%	0.19845		5.011%	50,113
								0.167%	1,670
Leadframe	EFTEC64T_PPF	長華	Copper(Cu)	7440-50-8	Balance(89% N	45.52475	46.34	39.002%	390,024
			Chromium(Cr)	7440-47-3	0.25%	0.11584		38.320%	383,199
			Tin(Sn)	7440-31-5	0.25%	0.11584		0.098%	975
			Zinc(Zn)	7440-66-6	0.20%	0.09267		0.098%	975
			Nickel(Ni)	7440-02-0	0.3-9.0%	0.23168		0.078%	780
			Palladium(Pd)	7440-05-3	0.04-0.8%	0.23168		0.195%	1,950
			Gold(Au)	7440-57-5	0.001-0.1%	0.02317		0.195%	1,950
								0.020%	195
Die_1	Silicon		Silicon	7440-21-3	100%		4.97	4.183%	41,825
Die Attach 1	EN-4900G*	HITACHI	Silver(Ag)	7440-22-4	72-82%	0.65113	0.88	0.741%	7,407
			Acrylic resin	Trade secret	6-11%	0.07919		0.548%	5,481
			Polybutadiene derivative	Trade secret	2-9%	0.04400		0.067%	667
			Butadiene copolymer	Trade secret	< 2.0 %	0.01320		0.037%	370
			Acrylate	Trade secret	3-8%	0.05279		0.011%	111
			Epoxy resin	Trade secret	1-4%	0.02200		0.044%	444
			Peroxide	Trade secret	< 1.0%	0.00440		0.019%	185
			Additive	Trade secret	< 2.0%	0.01320		0.004%	37
								0.011%	111
Wire 1	Cu wire	NIPPON	Copper(Cu)	7440-50-8	≥96.55%	0.46545	0.47	0.393%	3,934
			Palladium(Pd)	7440-05-3	≤3.1%	0.00056		0.3918%	3,918
			Gold(Au)	7440-57-5	≤0.35%	0.00140		0.0005%	5
								0.0012%	12
Total							118.80	100%	1000000

DISCLAIMER

- The above material declaration can be used only as reference in identifying the Hazardous material content of the product.
- ASE does not guarantee the Material composition accuracy as it is based on the data provided by outside sources and has not been validated.
- This material declaration does not include data from any active and passive component assembled in the package.
- Due to Leadframe and substrate is belong "re-make product" by other homogeneous material , so it's composition will be different with SDS